RX Capacitive Touch Evaluation System

Self-Capacitance Touch Buttons/Wheels/Slider Board

User's Manual

Renesas Solution Starter Kit RX Capacitive Touch Evaluation System Application Board

All information contained in these materials, including products and product specifications, represents information on the product at the time of publication and is subject to change by Renesas Electronics Corp. without notice. Please review the latest information published by Renesas Electronics Corp. through various means, including the Renesas Electronics Corp. website (http://www.renesas.com).

Notice

- 1. Descriptions of circuits, software and other related information in this document are provided only to illustrate the operation of semiconductor products and application examples. You are fully responsible for the incorporation of these circuits, software, and information in the design of your equipment. Renesas Electronics assumes no responsibility for any losses incurred by you or third parties arising from the use of these circuits, software, or information.
- 2. Renesas Electronics has used reasonable care in preparing the information included in this document, but Renesas Electronics does not warrant that such information is error free. Renesas Electronics assumes no liability whatsoever for any damages incurred by you resulting from errors in or omissions from the information included herein.
- 3. Renesas Electronics does not assume any liability for infringement of patents, copyrights, or other intellectual property rights of third parties by or arising from the use of Renesas Electronics products or technical information described in this document. No license, express, implied or otherwise, is granted hereby under any patents, copyrights or other intellectual property rights of Renesas Electronics or others.
- 4. You should not alter, modify, copy, or otherwise misappropriate any Renesas Electronics product, whether in whole or in part. Renesas Electronics assumes no responsibility for any losses incurred by you or third parties arising from such alteration, modification, copy or otherwise misappropriation of Renesas Electronics product.
- 5. Renesas Electronics products are classified according to the following two quality grades: "Standard" and "High Quality". The recommended applications for each Renesas Electronics product depends on the product's quality grade, as indicated below.

"Standard": Computers; office equipment; communications equipment; test and measurement equipment; audio and visual equipment; home electronic appliances; machine tools; personal electronic equipment; and industrial robots etc.

"High Quality": Transportation equipment (automobiles, trains, ships, etc.); traffic control systems; anti-disaster systems; anticrime systems; and safety equipment etc.

Renesas Electronics products are neither intended nor authorized for use in products or systems that may pose a direct threat to human life or bodily injury (artificial life support devices or systems, surgical implantations etc.), or may cause serious property damages (nuclear reactor control systems, military equipment etc.). You must check the quality grade of each Renesas Electronics product before using it in a particular application. You may not use any Renesas Electronics product for any application for which it is not intended. Renesas Electronics shall not be in any way liable for any damages or losses incurred by you or third parties arising from the use of any Renesas Electronics product for which the product is not intended by Renesas Electronics.

- 6. You should use the Renesas Electronics products described in this document within the range specified by Renesas Electronics, especially with respect to the maximum rating, operating supply voltage range, movement power voltage range, heat radiation characteristics, installation and other product characteristics. Renesas Electronics shall have no liability for malfunctions or damages arising out of the use of Renesas Electronics products beyond such specified ranges.
- 7. Although Renesas Electronics endeavors to improve the quality and reliability of its products, semiconductor products have specific characteristics such as the occurrence of failure at a certain rate and malfunctions under certain use conditions. Further, Renesas Electronics products are not subject to radiation resistance design. Please be sure to implement safety measures to guard them against the possibility of physical injury, and injury or damage caused by fire in the event of the failure of a Renesas Electronics product, such as safety design for hardware and software including but not limited to redundancy, fire control and malfunction prevention, appropriate treatment for aging degradation or any other appropriate measures. Because the evaluation of microcomputer software alone is very difficult, please evaluate the safety of the final products or systems manufactured by you.
- 8. Please contact a Renesas Electronics sales office for details as to environmental matters such as the environmental compatibility of each Renesas Electronics product. Please use Renesas Electronics products in compliance with all applicable laws and regulations that regulate the inclusion or use of controlled substances, including without limitation, the EU RoHS Directive. Renesas Electronics assumes no liability for damages or losses occurring as a result of your noncompliance with applicable laws and regulations.
- 9. Renesas Electronics products and technology may not be used for or incorporated into any products or systems whose manufacture, use, or sale is prohibited under any applicable domestic or foreign laws or regulations. You should not use Renesas Electronics products or technology described in this document for any purpose relating to military applications or use by the military, including but not limited to the development of weapons of mass destruction. When exporting the Renesas Electronics products or technology described in this document, you should comply with the applicable export control laws and regulations and follow the procedures required by such laws and regulations.
- 10. It is the responsibility of the buyer or distributor of Renesas Electronics products, who distributes, disposes of, or otherwise places the product with a third party, to notify such third party in advance of the contents and conditions set forth in this document, Renesas Electronics assumes no responsibility for any losses incurred by you or third parties as a result of unauthorized use of Renesas Electronics products.
- 11. This document may not be reproduced or duplicated in any form, in whole or in part, without prior written consent of Renesas Electronics.
- 12. Please contact a Renesas Electronics sales office if you have any questions regarding the information contained in this document or Renesas Electronics products, or if you have any other inquiries.
- (Note 1) "Renesas Electronics" as used in this document means Renesas Electronics Corporation and also includes its majorityowned subsidiaries.
- (Note 2) "Renesas Electronics product(s)" means any product developed or manufactured by or for Renesas Electronics.

General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Handling of Unused Pins

Handle unused pins in accordance with the directions given under Handling of Unused Pins in the manual.

The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible. Unused pins should be handled as described under Handling of Unused Pins in the manual.

2. Processing at Power-on

The state of the product is undefined at the moment when power is supplied.

The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the moment when power is supplied.

In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the moment when power is supplied until the reset process is completed.

In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the moment when power is supplied until the power reaches the level at which resetting has been specified.

3. Prohibition of Access to Reserved Addresses

Access to reserved addresses is prohibited.

The reserved addresses are provided for the possible future expansion of functions. Do not access these addresses; the correct operation of LSI is not guaranteed if they are accessed.

4. Clock Signals

After applying a reset, only release the reset line after the operating clock signal has become stable. When switching the clock signal during program execution, wait until the target clock signal has stabilized.

When the clock signal is generated with an external resonator (or from an external oscillator) during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Moreover, when switching to a clock signal produced with an external resonator (or by an external oscillator) while program execution is in progress, wait until the target clock signal is stable.

5. Differences between Products

Before changing from one product to another, i.e. to a product with a different part number, confirm that the change will not lead to problems.

The characteristics of Microprocessing unit or Microcontroller unit products in the same group but having a different part number may differ in terms of the internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

How to Use This Manual

1. Purpose and Target Readers

This manual is designed to provide the user with a general understanding of the Capacitive Touch Application Board and its electrical characteristics. It is intended for users designing sample code on the RSSK platform, using the many different incorporated peripheral devices.

The manual includes an overview of the Capacitive Touch Application Board functions, but does not serve as a guide for embedded programming or hardware design. A basic knowledge of electric circuits, logical circuits, and MCUs is necessary in order to use this manual.

Particular attention should be paid to the precautionary notes when using the manual. These notes occur within the body of the text, at the end of each section, and in the Usage Notes section.

The revision history summarizes the locations of revisions and additions. It does not list all revisions. Refer to the text of the manual for details.

The following documents apply to the Capacitive Touch Application Board included in the Renesas Capacitive Touch Evaluation System. Make sure to refer to the latest versions of these documents. The newest versions of the documents listed may be obtained from the Renesas Electronics Web site.

Document Type	Description	Document Title	Document No.
User's manual	hardware specifications	RX Capacitive Touch Evaluation System: Self- Capacitance	This User's Manual
		Buttons/Wheels/Slider Board User's Manual	

2. List of Abbreviations and Acronyms

Abbreviation	Full Form
ACIA	Asynchronous Communications Interface Adapter
bps	bits per second
CRC	Cyclic Redundancy Check
DMA	Direct Memory Access
DMAC	Direct Memory Access Controller
GSM	Global System for Mobile Communications
Hi-Z	High Impedance
IEBus	Inter Equipment Bus
I/O	Input/Output
IrDA	Infrared Data Association
LSB	Least Significant Bit
MSB	Most Significant Bit
NC	Non-Connect
PLL	Phase Locked Loop
PWM	Pulse Width Modulation
SFR	Special Function Register
SIM	Subscriber Identity Module
UART	Universal Asynchronous Receiver/Transmitter
VCO	Voltage Controlled Oscillator

All trademarks and registered trademarks are the property of their respective owners.

Table of Contents

1.	Ove	erview	1
	1.1	Purpose	1
	1.2	Features	1
2.	Boa	ard Layout	2
	2.1	Component Layout	2
	2.2	Overlay Dimensions	3
	2.3	Component Placement	4
3.	Boa	ard Attachment & Specifications	6
	3.1	Board Connection Configuration	6
4.	Hea	aders	7
	4.1	GPIO Interface	7
	4.2	CTSU Interface	7
5.	Circ	cuit Diagram	8
6.	PCI	B Layout Diagram	9
7.	Par	ts List10	0
8.	Add	ditional Information1	1

RENESAS

Self-Capacitance Touch Buttons/Wheels/Slider Board RX Capacitive Touch Evaluation System Application Board

R12UZ0005EJ0100 Rev.1.00 Feb 17, 2016

1. Overview

1.1 Purpose

This product was developed for use with a CPU board as an evaluation tool for the Renesas RX Capacitive Touch Evaluation System.

1.2 Features

This application board offers the following features:

- Connectable to the CPU board included in the Renesas RX Capacitive Touch Evaluation System
- Same interface as the CPU board included in Renesas RX Capacitive Touch Evaluation System
- Button/wheel/slider board
 - 3 self-capacitance button electrodes
 - 2 types of wheel electrodes (8-electrode and 4-electrode)
 - 1 slider electrode (5 electrodes)
- 3-mm thick acrylic overlay (attached)

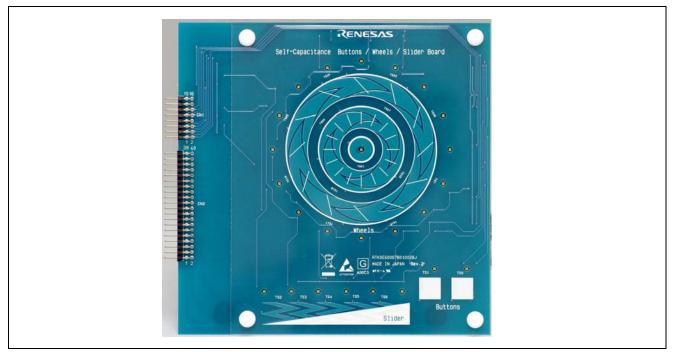


Figure 1.1 Application Board External Dimensions



2. Board Layout

2.1 Component Layout

Figure 2.1 shows the component layout of the application board.

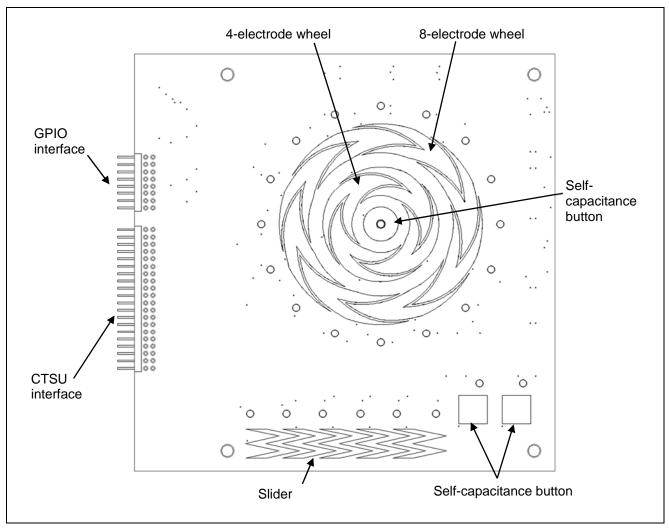


Figure 2.1 Component Layout



2.2 Overlay Dimensions

Figure 2.2 shows the dimensions of the overlay attached to the application board. Dimensions are shown in millimeters. Overlay thickness is 3.0 mm.

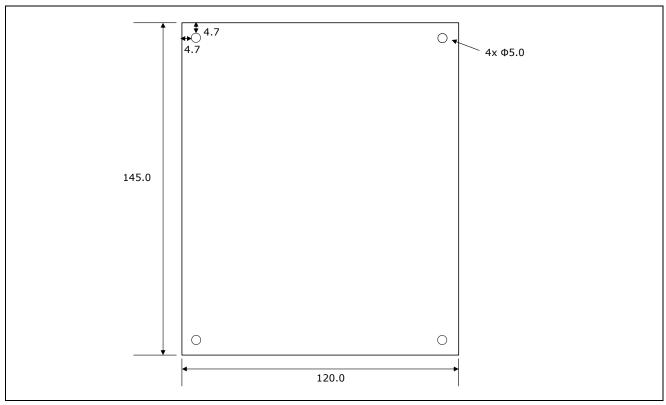


Figure 2.2 Overlay Dimensions



2.3 Component Placement

Figure 2.3 and Figure 2.4 show the placement of individual components on the application board.

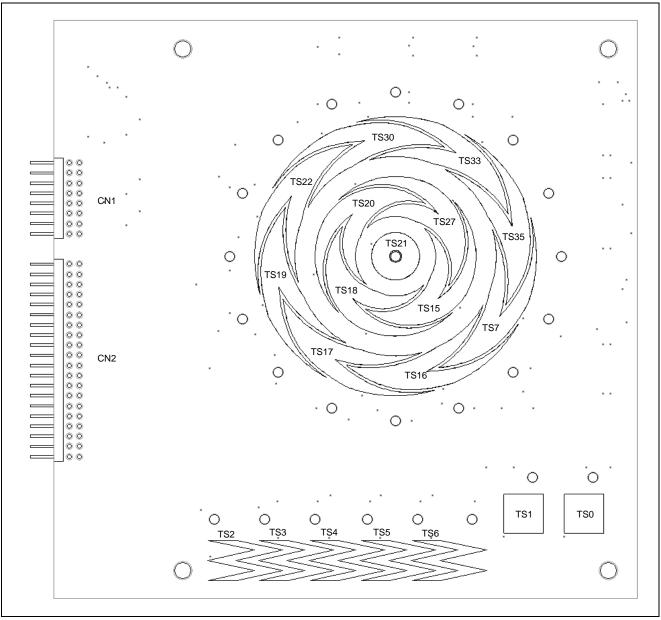


Figure 2.3 Application Board Component Placement (top/component side)



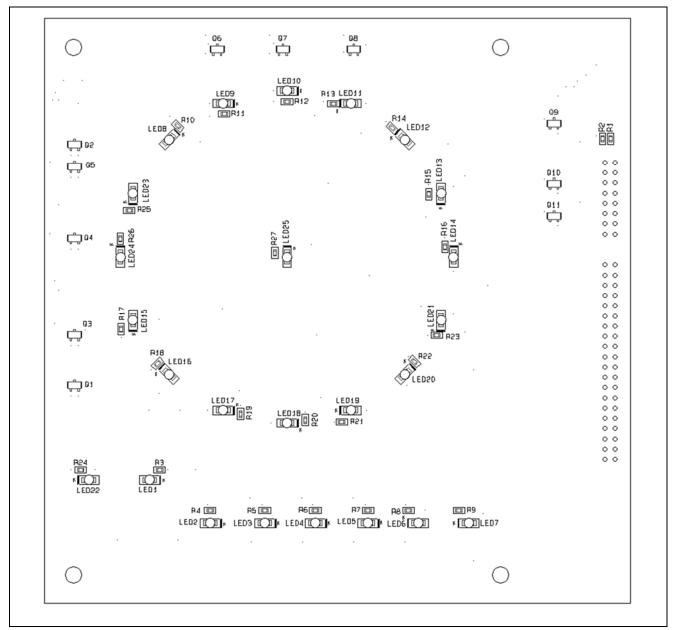


Figure 2.4 Application Board Component Placement (bottom/soldered side)



3. Board Attachment & Specifications

3.1 Board Connection Configuration

Insert headers CN1 and CN2 on the application board into the corresponding CN1 and CN2 sockets on the CPU board. Make sure both headers are inserted to match the direction and number of pins on the corresponding connectors and that the pins are fully inserted into the sockets.

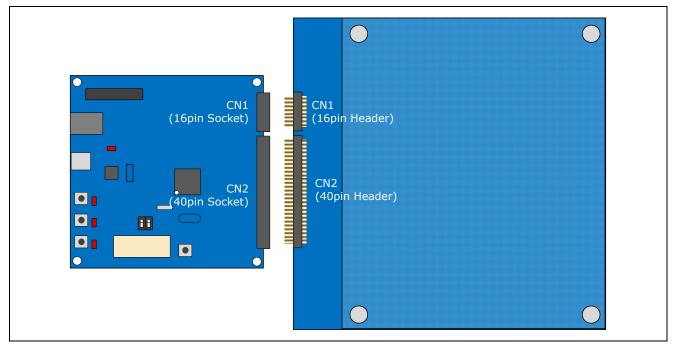


Figure 3.1 Board Connection Direction

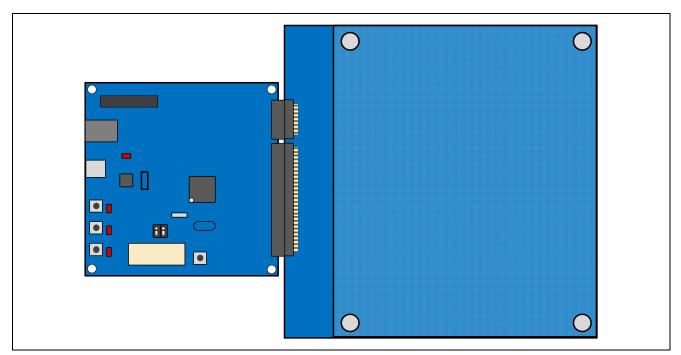


Figure 3.2 Connected Boards



4. Headers

Header names (circuit net names) differ for the application board and the CPU board. This section provides details on all headers; the following information can serve as verification tables when using the extension board function.

4.1 GPIO Interface

Table 4.1 Application Headers (CN1)

Pin	Header Name	Pin	Header Name
1	LED_LOW0	2	LED_LOW 1
3	LED_LOW 2	4	LED_LOW 3
5	LED_LOW 4	6	LED_LOW 5
7	LED_LOW 6	8	-
9	LED_COL1	10	LED_COL2
11	LED_COL3	12	LED_COL4
13	-	14	ADC
15	VCC_LED	16	VSS_GND

- : Non Connection

4.2 CTSU Interface

Table 4.2Application Headers (CN2)

Pin	Header Name	Pin	Header Name
1	TS0	2	TS1
3	TS2	4	TS3
5	TS4	6	TS5
7	TS6	8	TS7
9	-	10	-
11	-	12	-
13	-	14	-
15	-	16	TS15
17	TS16	18	TS17
19	TS18	20	TS19
21	TS20	22	TS21
23	TS22	24	-
25	-	26	-
27	-	28	TS27
29	-	30	-
31	TS30	32	-
33	-	34	TS33
35	-	36	TS35
37	-	38	-
39	-	40	-

- : Non Connection



5. Circuit Diagram

The circuit diagram is shown on the Appendix 1.



6. PCB Layout Diagram

The PCB layout diagram is shown on the Appendix 2.



7. Parts List

The parts list is shown on the Appendix 3.



8. Additional Information

Technical Support

For more information about how to use the application board, refer to the CD/DVD included with this product or to the Renesas website.

For information about the target microcontroller, refer to the corresponding User's Hardware Manual.

For information about Assembler language, refer to the RX Family User's Software Manual.

For information about Workbench6, refer to the Workbench6 Capacitance Touch Integrated Development Environment User's Manual.

Online tech support and other information is available at the following website: http://www.renesas.com/

You can also send technical inquiries to the following email addresses:

csc@renesas.com

General information on Renesas Microcontrollers can be found on the Renesas website at: http://www.renesas.com/

Trademarks

All brand or product names used in this manual are trademarks or registered trademarks of their respective companies or organisations.

Copyright

This document may be, wholly or partially, subject to change without notice. All rights reserved. Duplication of this document, either in whole or part is prohibited without the written permission of Renesas Electronics Limited.

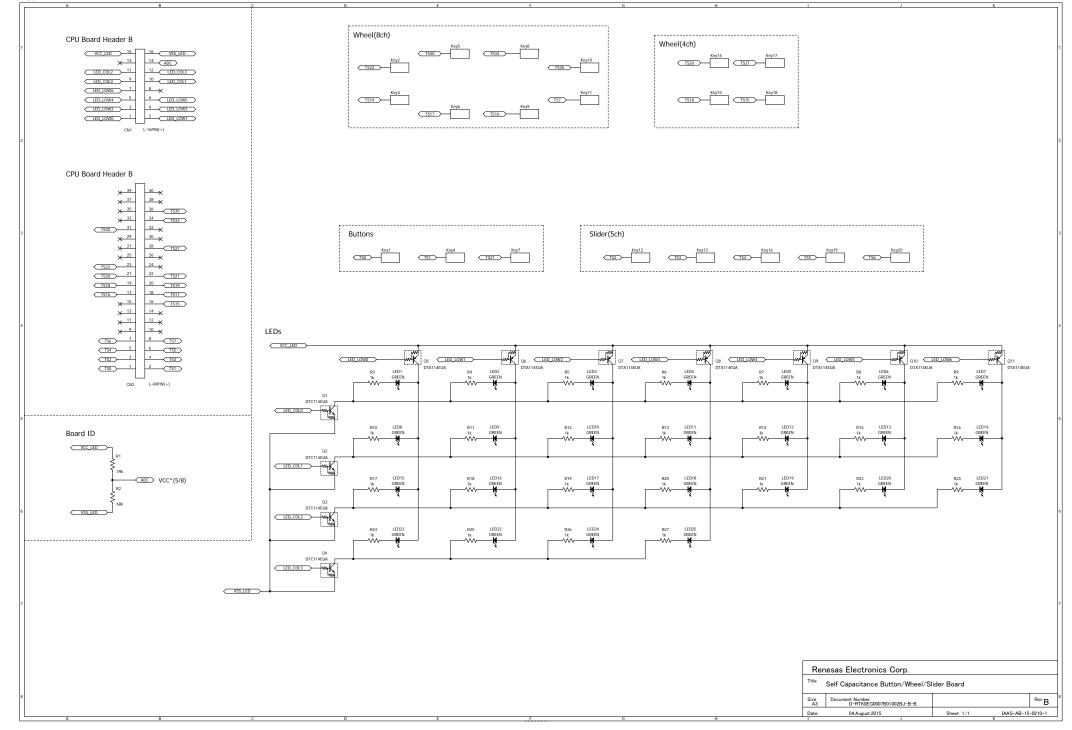
© 2016 Renesas Electronics Europe Limited. All rights reserved.

© 2016 Renesas Electronics Corporation. All rights reserved.

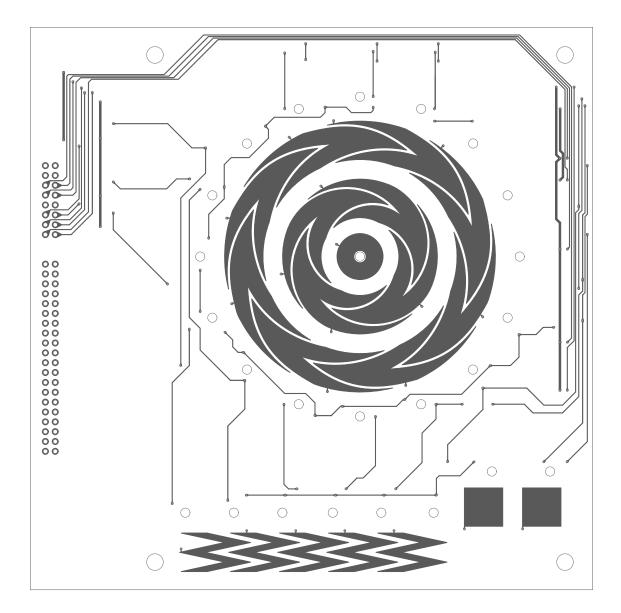
© 2016 Renesas System Design Co., Ltd. All rights reserved.



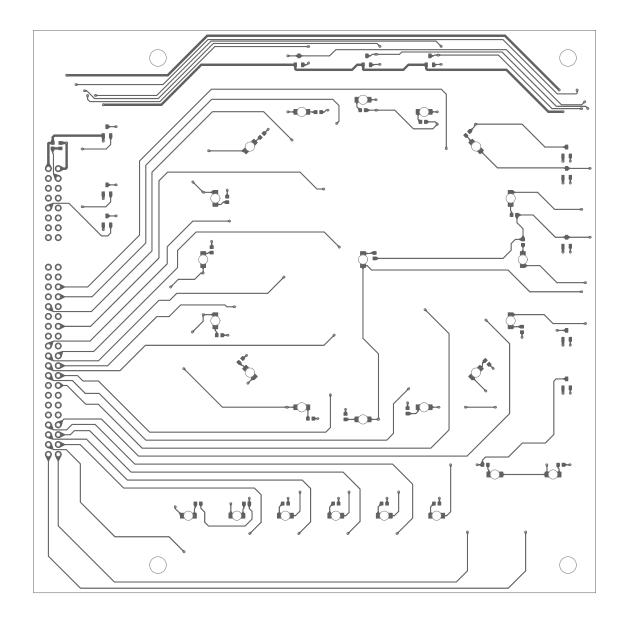
Appendix 1.







PCB Top-side Layout



PCB Bottom-side Layout

Appendix 3. PertNo RTK0EG0007B01002BJ Title Self-Capacitance Buttons/Wheels/Slider Board No Component Name Component Specification Mount/Unmount Oty/Set Remark 1 Right Angle Pin Header ON2 PSR-420256-08 Hirosugi-Keiki Mount 1 Horosugi-Keiki Mount 1 Horosugi-Keiki Mount 1 Bight Angle Pin Header ON2 PSR-420256-0 Hirosugi-Keiki Mount 1 Bight Angle Pin Header ON2 PSR-42026-2 Hirosugi-Keiki Mount 1 Bight Angle Pin Header ON2 PSR-42026-2 Hirosugi-Keiki Mount 1 Bight Angle Pin Header ON2 PSR-42026-2 Hirosugi-Keiki Mount 1 Bight Angle Pin Header ON2 PSR-42026-2 Hirosugi-Keiki Mount 1 Bight Angle Pin Header ON2 PSR-42026-2 Hirosugi-Keiki Mount 1 Bight Angle Pin Header ON4 Mount 1 Bight Angle Pin Header ON4 Mount 1 Mount Set Records Pin Pin Header N N N	
NoTypeReferenceProduct Number (Specfication)ManufactureMount/UnmountQty/SetRemar1Right Angle Pin HeaderCN1PSR-420256-08Hirosugi-KeikiMount116-pin(2x8), 2.52Right Angle Pin HeaderCN2PSR-420256-20Hirosugi-KeikiMount140pin(2x20), 2.53Chip ResistorR1MCR03ERTJ393ROHMMount139k4Chip ResistorR2MCR03ERTJ683ROHMMount168k5Chip ResistorR3-R27MCR03ERTJ102ROHMMount251k6LEDLED1-LED25SML-812MTROHMMount25Green, Reverse-mount av7TransistorQ1-Q4DTC114EKAROHMMount7PNP9Touch ElectrodeKey1-20Mount20	d BOM
2Right Angle Pin HeaderCN2PSR-420256-20Hirosugi-KeikiMount140pin(2x20), 2.53Chip ResistorR1MCR03ERTJ393ROHMMount139k4Chip ResistorR2MCR03ERTJ683ROHMMount168k5Chip ResistorR3-R27MCR03ERTJ102ROHMMount251k6LEDLED1-LED25SML-812MTROHMMount25Green, Reverse-mount av7TransistorQ1-Q4DTC114EKAROHMMount4NPN8TransistorQ5-Q11DTA114EKAROHMMount7PNP9Touch ElectrodeKey1-20Mount20	ks
3Chip ResistorR1MCR03ERTJ393R0HMMount139k4Chip ResistorR2MCR03ERTJ683R0HMMount168k5Chip ResistorR3-R27MCR03ERTJ102R0HMMount251k6LEDLED1-LED25SML-812MTR0HMMount25Green, Reverse-mount av7TransistorQ1-Q4DTC114EKAR0HMMount4NPN8TransistorQ5-Q11DTA114EKAR0HMMount7PNP9Touch ElectrodeKey1-20Mount20-	
4Chip ResistorR2MCR03ERTJ683R0HMMount168k5Chip ResistorR3-R27MCR03ERTJ102R0HMMount251k6LEDLED1-LED25SML-812MTR0HMMount25Green, Reverse-mount av7TransistorQ1-Q4DTC114EKAR0HMMount4NPN8TransistorQ5-Q11DTA114EKAR0HMMount7PNP9Touch ElectrodeKey1-20Mount20-	4mm-pitch
5Chip ResistorR3-R27MCR03ERTJ102ROHMMount251k6LEDLED1-LED25SML-812MTROHMMount25Green, Reverse-mount av7TransistorQ1-Q4DTC114EKAROHMMount4NPN8TransistorQ5-Q11DTA114EKAROHMMount7PNP9Touch ElectrodeKey1-20Mount20	
6LEDLED1-LED25SML-812MTROHMMount25Green, Reverse-mount av7TransistorQ1-Q4DTC114EKAROHMMount4NPN8TransistorQ5-Q11DTA114EKAROHMMount7PNP9Touch ElectrodeKey1-20Mount20	
7 Transistor Q1-Q4 DTC114EKA ROHM Mount 4 NPN 8 Transistor Q5-Q11 DTA114EKA ROHM Mount 7 PNP 9 Touch Electrode Key1-20 - - Mount 20 -	
8 Transistor Q5-Q11 DTA114EKA ROHM Mount 7 PNP 9 Touch Electrode Key1-20 - - Mount 20	ailable type
9 Touch Electrode Key1-20 - - Mount 20	
10PCBRTKOEG007B01002BJ REV.AMount1Image: Constraint of the system of the	
Image: series of the series	
Image: series of the series	
Image: series of the series	
Image: series of the series	
Image: series of the series	
Image: section of the section of th	
Image: series of the series	
Image: section of the section of th	
Image: series of the series	
Image: section of the section of th	
Image: series of the series	
Image: state of the state of	
Image: selection of the	
Image: selection of the	
Image: Section of the section of t	
Image: second	

Revision History Self-Capacitance Touch Buttons/Wheels/Slider Board User's Manual

Rev.	Date	Description	
		Page	
1.00	Feb 17, 2016	-	First Edition issued

Self-Capacitance Touch Button/Wheel/Slider Board User's Manual

Publication Date: Rev.1.00 Feb 17, 2016

Published by:Renesas Electronics Corporation 3-2-24 Toyosu, Koto Ward, Tokyo, 135-0061, Japan



Renesas Electronics Corporation

http://www.renesas.com

Refer to "http://www.renesas.com/" for the latest and detailed information.

SALES OFFICES

Renesas Electronics America Inc. 2801 Scott Boulevard Santa Clara, CA 95050-2549, U.S.A. Tel: +1-408-588-6000, Fax: +1-408-588-6130 Renesas Electronics Canada Limited 9251 Yonge Street, Suite 8309 Richmond Hill, Ontario Canada L4C 9T3 Tel: +1-905-237-2004 Renesas Electronics Europe Limited Dukes Meadow, Millboard Road, Bourne End, Buckinghamshire, SL8 5FH, U.K Tel: +44-1628-585-100, Fax: +44-1628-585-900 Renesas Electronics Europe GmbH Arcadiastrasse 10, 40472 Düsseldorf, Germany Tel: +49-211-6503-0, Fax: +49-211-6503-1327 Renesas Electronics (China) Co., Ltd. Room 1709, Quantum Plaza, No.27 ZhiChunLu Haidian District, Beijing 100191, P.R.China Tel: +86-10-8235-1155, Fax: +86-10-8235-7679 Renesas Electronics (Shanghai) Co., Ltd. Unit 301, Tower A, Central Towers, 555 Langao Road, Putuo District, Shanghai, P. R. China 200333 Tel: +86-21-2226-0888, Fax: +86-21-2226-0999 Renesas Electronics Hong Kong Limited Unit 1601-1611, 16/F., Tower 2, Grand Century Place, 193 Prince Edward Road West, Mongkok, Kowloon, Hong Kong Tel: +852-2265-6688, Fax: +852 2886-9022 Renesas Electronics Taiwan Co., Ltd. 13F, No. 363, Fu Shing North Road, Taipei 10543, Taiwan Tel: +886-2-8175-9600, Fax: +886 2-8175-9670 Renesas Electronics Singapore Pte. Ltd. 80 Bendemeer Road, Unit #06-02 Hyflux Innovation Centre, Singapore 339949 Tel: +65-6213-0200, Fax: +65-6213-0300 Renesas Electronics Malaysia Sdn.Bhd. Unit 1207, Block B, Menara Amcorp, Amcorp Trade Centre, No. 18, Jln Persiaran Barat, 46050 Petaling Jaya, Selangor Darul Ehsan, Malaysia Tel: +60-3-7955-9390, Fax: +60-3-7955-9510

Renesas Electronics India Pvt. Ltd. No.777C, 100 Feet Road, HALII Stage, Indiranagar, Bangalore, India Tel: +91-80-67208700, Fax: +91-80-67208777 Renesas Electronics Korea Co., Ltd. 12F., 234 Teheran-ro, Gangnam-Gu, Seoul, 135-080, Korea Tel: +82-2-558-3737, Fax: +82-2-558-5141

> © 2016 Renesas Electronics Corporation. All rights reserved. Colophon 4.0

RX Capacitive Touch Evaluation System

Self-Capacitance Touch Buttons/Wheels/Slider Board User's Manual

